

TECHNICAL CHARACTERISTICS

1. General Characteristics

Dimension: 13.28L x 13.70W x 2.60H mm

Weight: Approx. 0.38 g

Contact principle: Friction technology

Operating position: Shaft up / Down / Horizontal

Mounting System: SMT Type (without post)

Function: Push Pull Type

Durability: 5,000 cycles min.

2. Mechanical Characteristics

Insulation material: Thermoplastic, UL 94V-0

RoHS Directive 2011/65/EU Compliant

3. Electrical Characteristics

Number of contacts: 6, 8 pins (optional)

Contact resistance: 50 mΩ typical, 100 mΩ max.

Insulation resistance: >1000 MΩ / 500 VDC

4. Solderability

Wave: Not applicable

IR reflow: 260°C, 10 sec. Max.

Manual soldering: 360°C, 3 sec. Max.

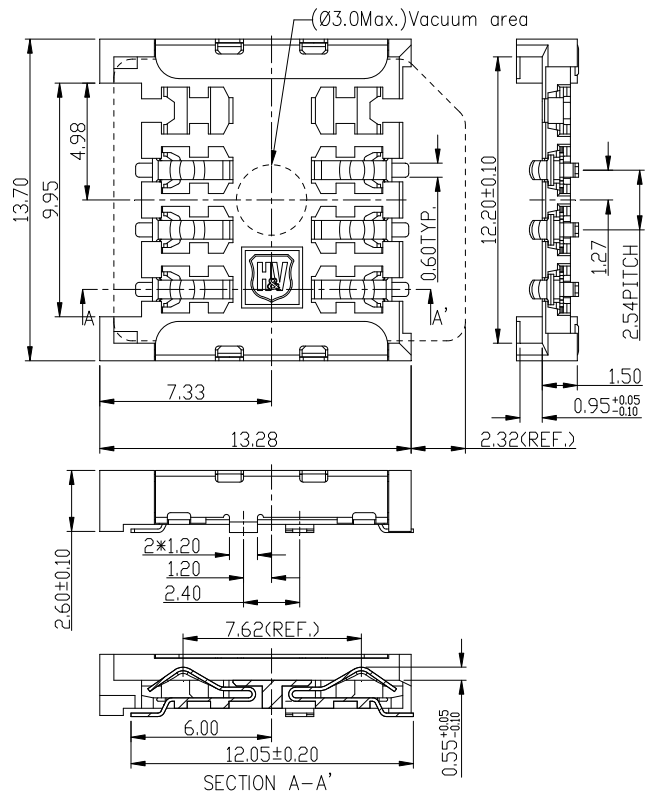
5. Environmental Characteristics

Operating temperature: - 40°C ~ + 85°C

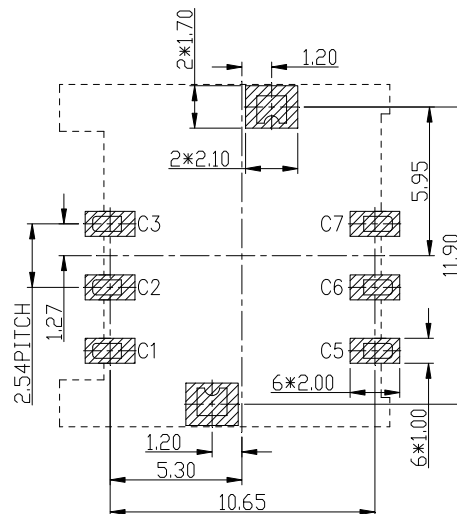
Operating humidity: 10 % ~ 95 % RH

Storage temperature: - 40°C ~ + 85°C

Storage humidity: 10 % ~ 95 % RH



Unit: mm; Tolerances: ±0.15 mm
Mechanical outline dimension



Unit: mm; Tolerances: ±0.05 mm
Reference dimension for PCB layout

H&V Micro SIM Card Connector

Model No.: ICC-M01 6Pin

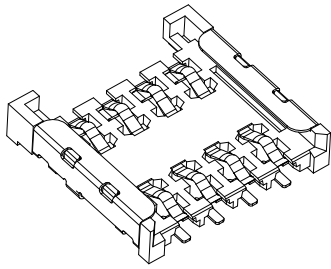
Revision: 1.2

Date: MAY 01, 2014

Note:

1. Coplanarity of solder pins 0.10mm max.

2. Recommended thickness of solder paste > 0.15mm.



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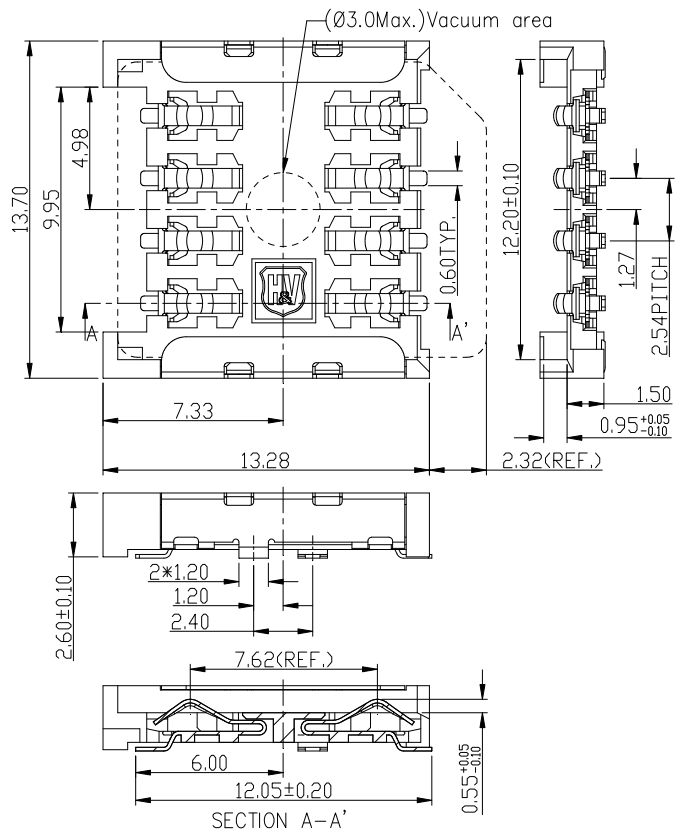
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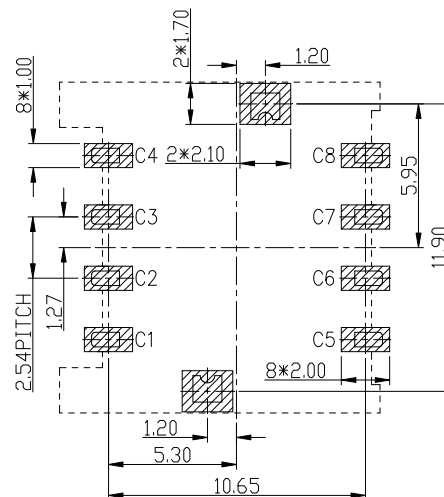
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H&V Micro SIM Card Connector

Model No.: ICC-M01 8Pin

Revision: 1.2

Date: MAY 01, 2014

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